

Amendments In the Claims

1. (Currently Amended) A method comprising:
forming a tungsten plug in a dielectric layer;
forming an electrically conductive interconnect line on the dielectric layer after formation
of the tungsten plug, wherein the tungsten plug is electrically connected to the
electrically conductive interconnect line;
contacting the electrically conductive interconnect line with liquid water after formation
of the electrically conductive interconnect line;
contacting the electrically conductive interconnect line with a solution to remove residual
polymer after the electrically conductive interconnect line is contacted with the
liquid water;
wherein the electrically conductive interconnect line is contacted with the liquid water for
less than 120 minutes.
2. (Currently Amended) The method of claim 1 wherein the liquid water is
degasified and deionized.
3. (Currently Amended) The method of claim 1 wherein the liquid water is
deionized but not degasified.
4. (Currently Amended) The method of claim 1 wherein the liquid water is
degasified but not deionized.
5. (Currently Amended) The method of claim 1 wherein the liquid water is neither
degasified nor deionized.
6. (Currently Amended) The method of claim 1 wherein the liquid water has a pH
that is at or near neutral.

7. (Currently Amended) The method of claim 1 wherein the electrically conductive interconnect line is contacted with the liquid water for less than 60 minutes.

8. (Currently Amended) The method of claim 1 wherein the electrically conductive interconnect line is contacted with the liquid water for less than 15 minutes.

9. (Original) The method of claim 1 wherein the electrically conductive interconnect line is formed from a metal stack that includes one or more of titanium, titanium nitride, aluminum, an aluminum copper alloy, and an aluminum silicon copper alloy.

10. - 26. (Canceled).